SUBMINIATURE SOLID STATE LAMP

Part Number: KM2520SECK09

Super Bright Orange

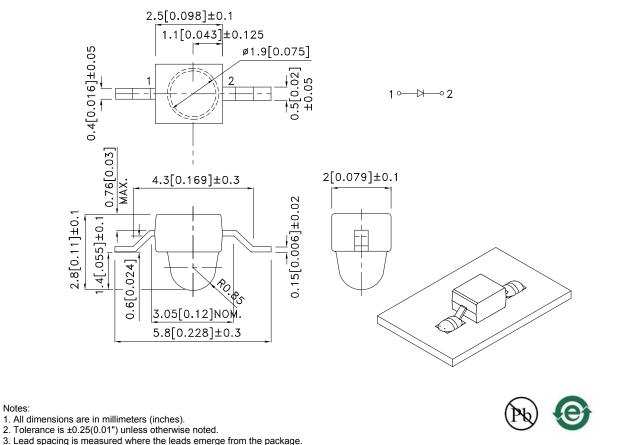
Features

- Subminiature package.
- Z-bend lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. 5. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAD0278 **APPROVED: WYNEC**

Notes:

REV NO: V.8 CHECKED: Allen Liu DATE: DEC/21/2010 DRAWN: Y.H.Wu

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Selection Guide

Delection Oulde							
Part No.	No. Dice		lv (mcd) [2] @ 20mA		· /···		Viewing Angle [1]
			Min.	Тур.	201/2		
KM2520SECK09	Super Bright Orange (AlGaInP)	Water Clear	1900	2700	20°		

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

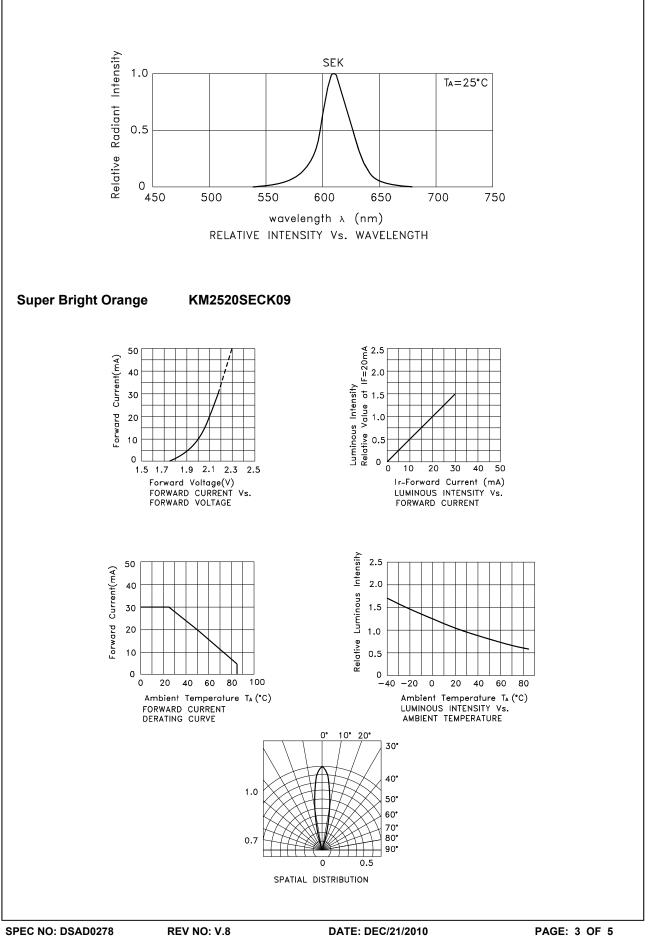
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	I⊧=20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	195	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

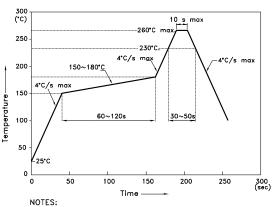
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KM2520SECK09

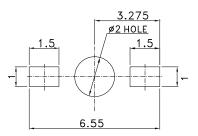
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

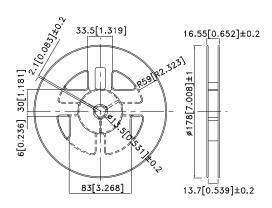


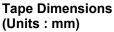
Time _____ NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to be temperature to high temperature. 3.Number of reflow process shall be 2 times or less.

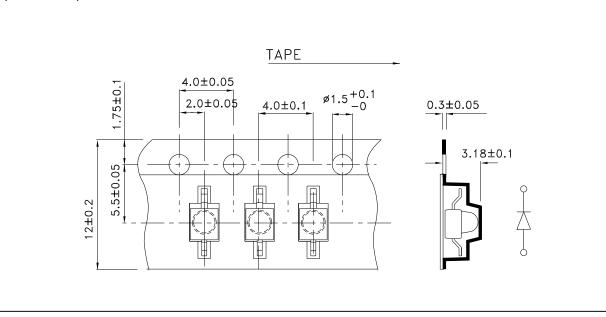












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